

CM1216

6 and 8-Channel Low Capacitance ESD Arrays

Product Description

The CM1216 family of diode arrays provide sESD protection for electronic components or sub-systems requiring minimal capacitive loading. These devices are ideal for protecting systems with high data and clock rates or for circuits requiring low capacitive loading. Each ESD channel consists of a pair of diodes in series which steer the positive or negative ESD current pulse to either the positive (V_P) or negative (V_N) supply rail. The CM1216 protects against ESD pulses up to ± 15 kV per the IEC 61000-4-2 standard.

This device is particularly well-suited for protecting systems using high-speed ports such as USB2.0, IEEE1394 (Firewire[®], iLink[™]), Serial ATA, DVI, HDMI and corresponding ports in removable storage, digital camcorders, DVD-RW drives and other applications where extremely low loading capacitance with ESD protection are required in a small package footprint.

Features

- Six and Eight Channels of ESD Protection
- Provides ± 15 kV ESD Protection on Each Channel per the IEC 61000-4-2 ESD Requirements
- Channel Loading Capacitance of 1.6 pF Typical
- Channel I/O to GND Capacitance Difference of 0.04 pF Typical
- Mutual Capacitance of 0.13 pF Typical
- Minimal Capacitance Change with Temperature and Voltage
- Each I/O Pin Can Withstand Over 1000 ESD Strikes
- SOIC and MSOP Packages
- These Devices are Pb-Free and are RoHS Compliant

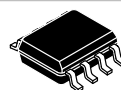
Applications

- IEEE1394 Firewire[®] Ports at 400 Mbps / 800 Mbps
- DVI Ports, HDMI Ports in Notebooks, Set Top Boxes, Digital TVs, LCD Displays
- Serial ATA Ports in Desktop PCs and Hard Disk Drives
- PCI Express Ports
- General Purpose High-Speed Data Line ESD Protection

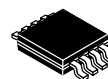


ON Semiconductor[®]

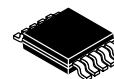
<http://onsemi.com>



SOIC-8
SM SUFFIX
CASE 751AC

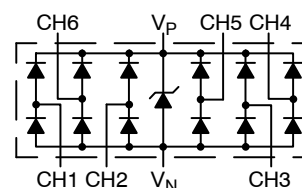


MSOP-8
MR SUFFIX
CASE 846AD

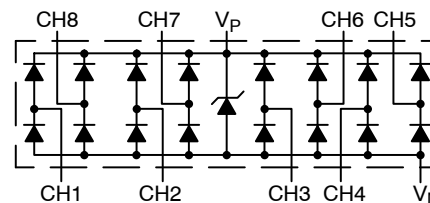


MSOP-10
MR SUFFIX
CASE 846AE

BLOCK DIAGRAM

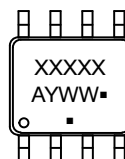


CM1216-06SM
CM1216-06MR



CM1216-08MR

MARKING DIAGRAM



XXXXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb-Free Package

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|----------------|-----------------------|
| CM1216-06SM | SOIC (Pb-Free) | 2500/Tape & Reel |
| CM1216-06MR | MSOP (Pb-Free) | 4000/Tape & Reel |
| CM1216-08MR | MSOP (Pb-Free) | 4000/Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

CM1216

PACKAGE / PINOUT DIAGRAMS

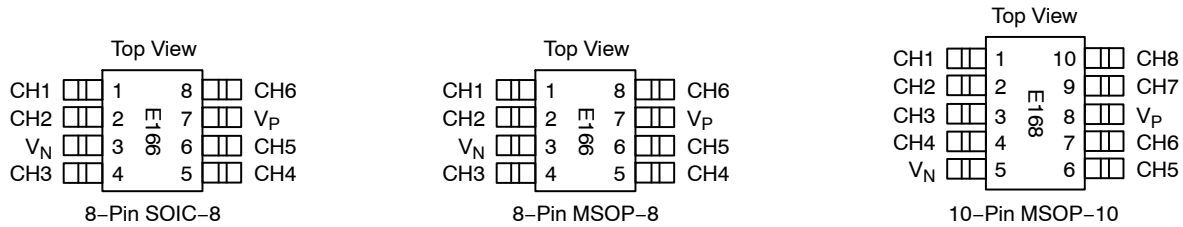


Table 1. PIN DESCRIPTIONS

| Pin Name | MSOP-8 | SOIC-8 | MSOP-10 | Type | Description |
|----------------|---------|---------|---------|------|------------------------------|
| | Pin No. | Pin No. | Pin No. | | |
| CH1 | 1 | 1 | 1 | I/O | ESD Channel |
| CH2 | 2 | 2 | 2 | I/O | ESD Channel |
| CH3 | 4 | 4 | 3 | I/O | ESD Channel |
| CH4 | 5 | 5 | 4 | I/O | ESD Channel |
| V _N | 3 | 3 | 5 | GND | Negative voltage supply rail |
| CH5 | 6 | 6 | 6 | I/O | ESD Channel |
| CH6 | 8 | 8 | 7 | I/O | ESD Channel |
| V _P | 7 | 7 | 8 | PWR | Positive voltage supply rail |
| CH7 | - | - | 9 | I/O | ESD Channel |
| CH8 | - | - | 10 | I/O | ESD Channel |

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

| Parameter | Rating | Units |
|--|--|-------|
| Operating Supply Voltage (V _P -V _N) | 6 | V |
| Diode Forward DC Current | 20 | μA |
| DC Voltage at any Channel Input | (V _N -0.5) to (V _P +0.5) | V |
| Operating Temperature Range Ambient Junction | -40 to +85 -40 to +125 | °C |
| Storage Temperature Range | -40 to +150 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

| Parameter | Rating | Units |
|--|-------------------|-------|
| Temperature Range (Ambient) | -40 to +85 | °C |
| Package Power Rating MSOP8 Package (CM1216-06MR) SOIC8 Package (CM1216-06SM) MSOP10 Package (CM1216-08MR) | 400 600 400 | mW |

CM1216

Table 4. ELECTRICAL OPERATING CHARACTERISTICS (Note 1)

| Symbol | Parameter | Conditions | Min | Typ | Max | Units |
|-----------------|---|--|------------|--------------|--------------|---------------|
| V_P | Operating Supply Voltage ($V_P - V_N$) | | | 3.3 | 5.5 | V |
| I_P | Operating Supply Current | $(V_P - V_N) = 3.3\text{ V}$ | | | 8 | μA |
| V_F | Diode Forward Voltage Top Diode Bottom Diode | $I_F = 20\ \mu\text{A}; T_A = 25^\circ\text{C}$ | 0.6 0.6 | 0.8 0.8 | 0.95 0.95 | V |
| I_{LEAK} | Channel Leakage Current | $T_A = 25^\circ\text{C}; V_P = 5\text{ V}, V_N = 0\text{ V}$ | | ± 0.1 | ± 1.0 | μA |
| C_{IN} | Channel Input Capacitance | At 1 MHz, $V_P = 3.3\text{ V}, V_N = 0\text{ V}, V_{IN} = 1.65\text{ V}$ (Note 2) | | 1.6 | 2.0 | pF |
| ΔC_{IN} | Channel Input Capacitance Matching | | | 0.04 | | pF |
| C_{MUTUAL} | Mutual Capacitance | $(V_P - V_N) = 3.3\text{ V}$ | | 0.13 | | pF |
| V_{ESD} | ESD Protection Peak Discharge Voltage at any channel input, in system, contact discharge per IEC 61000-4-2 standard | $T_A = 25^\circ\text{C}$ (Notes 2 and 3) | ± 15 | | | kV |
| V_{CL} | Channel Clamp Voltage Positive Transients Negative Transients | $I_{PP} = 1\text{ A}, t_P = 8/20\ \mu\text{S}; T_A = 25^\circ\text{C}$ | | +9.0 -1.5 | | V |
| R_{DYN} | Dynamic Resistance Positive transients Negative transients | $I_{PP} = 1\text{ A}, t_P = 8/20\ \mu\text{S}; T_A = 25^\circ\text{C}$ | | 0.6 0.4 | | Ω |

1. All parameters specified at $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$ unless otherwise noted.
2. Standard IEC 61000-4-2 with $C_{Discharge} = 150\text{ pF}$, $R_{Discharge} = 330\ \Omega$, $V_P = 3.3\text{ V}$, V_N grounded.
3. From I/O pins to V_P or V_N only. V_P bypassed to V_N with low ESR $0.2\ \mu\text{F}$ ceramic capacitor.

PERFORMANCE CHARACTERISTICS

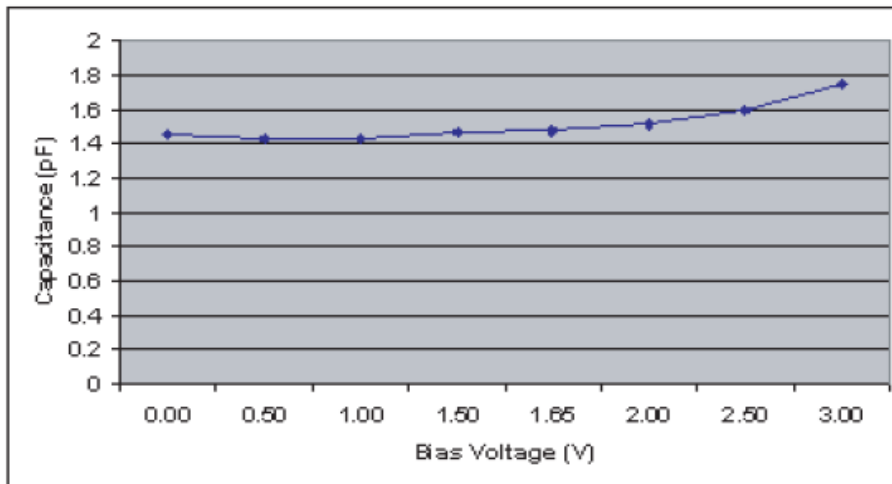


Figure 1. Typical Variation of C_{IN} vs. V_{IN}
($f = 1\text{ MHz}, V_P = 3.3\text{ V}, V_N = 0\text{ V}, 0.1\ \mu\text{F}$ Chip Capacitor between V_P and $V_N, T_A = 25^\circ\text{C}$)

APPLICATION INFORMATION

Design Considerations

In order to realize the maximum protection against ESD pulses, care must be taken in the PCB layout to minimize parasitic series inductances on the Supply/Ground rails as well as the signal trace segment between the signal input (typically a connector) and the ESD protection device. Refer to Application of Positive ESD Pulse between Input Channel and Ground, which illustrates an example of a positive ESD pulse striking an input channel. The parasitic series inductance back to the power supply is represented by L_1 and L_2 . The voltage V_{CL} on the line being protected is:

$$V_{CL} = \text{Fwd voltage drop of } D_1 + V_{\text{SUPPLY}} + L_1 \times d(I_{\text{ESD}}) / dt + L_2 \times d(I_{\text{ESD}}) / dt$$

where I_{ESD} is the ESD current pulse, and V_{SUPPLY} is the positive supply voltage.

An ESD current pulse can rise from zero to its peak value in a very short time. As an example, a level 4 contact discharge per the IEC61000-4-2 standard results in a current pulse that rises from zero to 30 Amps in 1 ns. Here $d(I_{\text{ESD}})/dt$ can be approximated by $\Delta I_{\text{ESD}}/\Delta t$, or $30/(1 \times 10^{-9})$. So just 10 nH of series inductance (L_1 and L_2 combined) will lead to a 300 V increment in V_{CL} !

Similarly for negative ESD pulses, parasitic series inductance from the V_N pin to the ground rail will lead to drastically increased negative voltage on the line being protected.

The CM1213 has an integrated Zener diode between V_P and V_N . This greatly reduces the effect of supply rail inductance L_2 on V_{CL} by clamping V_P at the breakdown voltage of the Zener diode. However, for the lowest possible V_{CL} , especially when V_P is biased at a voltage significantly below the Zener breakdown voltage, it is recommended that a 0.22 μF ceramic chip capacitor be connected between V_P and the ground plane.

As a general rule, the ESD Protection Array should be located as close as possible to the point of entry of expected electrostatic discharges. The power supply bypass capacitor mentioned above should be as close to the V_P pin of the Protection Array as possible, with minimum PCB trace lengths to the power supply, ground planes and between the signal input and the ESD device to minimize stray series inductance.

Additional Information

See also ON Semiconductor Application Note, "Design Considerations for ESD Protection", in the Applications section.

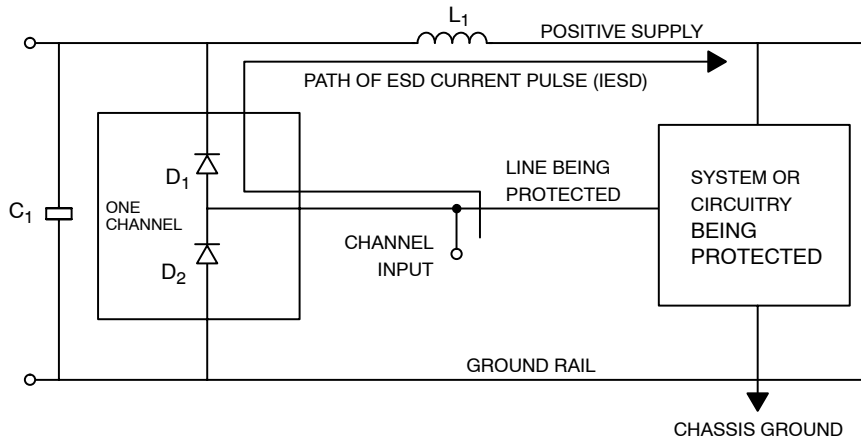
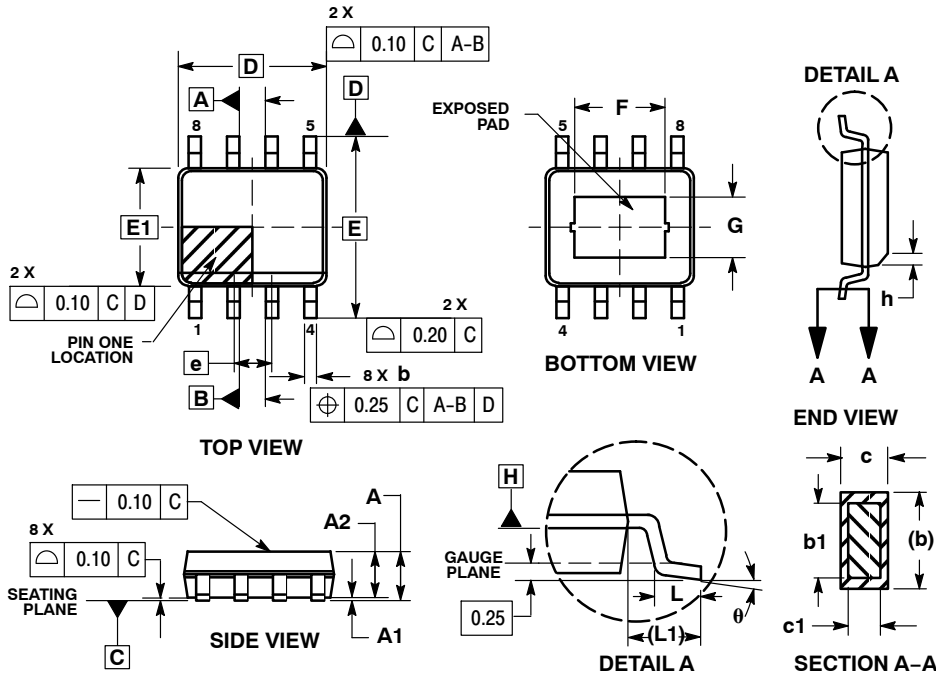


Figure 2. Application of Positive ESD Pulse between Input Channel and Ground

CM1216

PACKAGE DIMENSIONS

SOIC-8 EP
CASE 751AC-01
ISSUE B

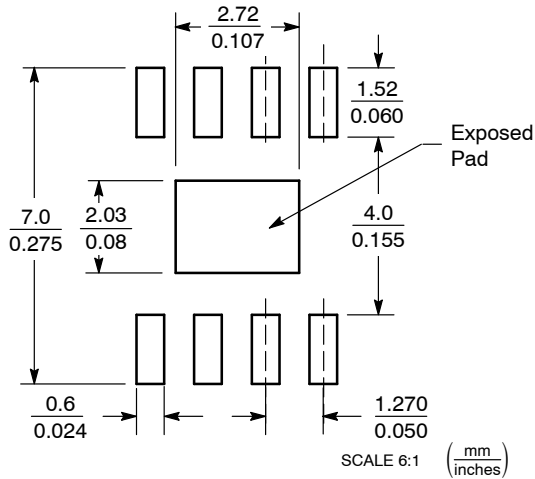


NOTES:

1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. DIMENSIONS IN MILLIMETERS (ANGLES IN DEGREES).
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 MM TOTAL IN EXCESS OF THE "b" DIMENSION AT MAXIMUM MATERIAL CONDITION.
4. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE H.

| DIM | MILLIMETERS | |
|----------|-------------|------|
| | MIN | MAX |
| A | 1.35 | 1.75 |
| A1 | 0.00 | 0.10 |
| A2 | 1.35 | 1.65 |
| b | 0.31 | 0.51 |
| b1 | 0.28 | 0.48 |
| c | 0.17 | 0.25 |
| c1 | 0.17 | 0.23 |
| D | 4.90 BSC | |
| E | 6.00 BSC | |
| E1 | 3.90 BSC | |
| e | 1.27 BSC | |
| L | 0.40 | 1.27 |
| L1 | 1.04 REF | |
| F | 2.24 | 3.20 |
| G | 1.55 | 2.51 |
| h | 0.25 | 0.50 |
| θ | 0° | 8° |

SOLDERING FOOTPRINT*

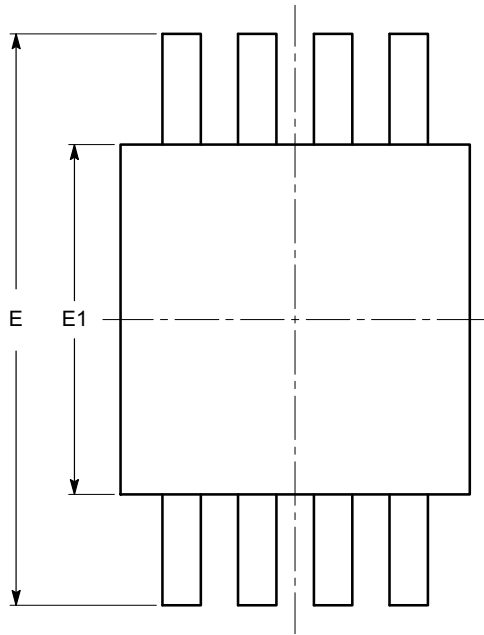


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

CM1216

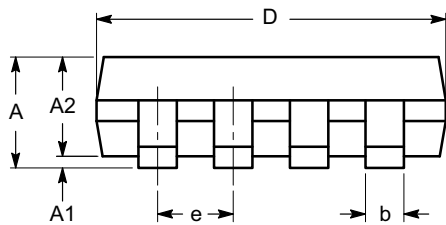
PACKAGE DIMENSIONS

MSOP 8, 3x3
CASE 846AD-01
ISSUE O

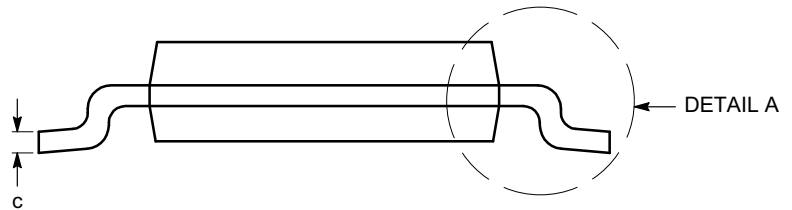


TOP VIEW

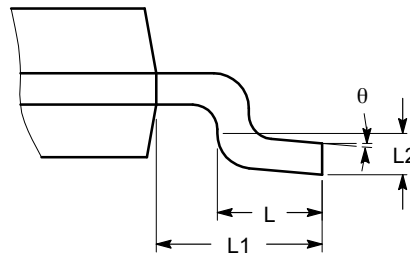
| SYMBOL | MIN | NOM | MAX |
|----------|----------|------|------|
| A | | | 1.10 |
| A1 | 0.05 | 0.10 | 0.15 |
| A2 | 0.75 | 0.85 | 0.95 |
| b | 0.22 | | 0.38 |
| c | 0.13 | | 0.23 |
| D | 2.90 | 3.00 | 3.10 |
| E | 4.80 | 4.90 | 5.00 |
| E1 | 2.90 | 3.00 | 3.10 |
| e | 0.65 BSC | | |
| L | 0.40 | 0.60 | 0.80 |
| L1 | 0.95 REF | | |
| L2 | 0.25 BSC | | |
| θ | 0° | | 6° |



SIDE VIEW



END VIEW



DETAIL A

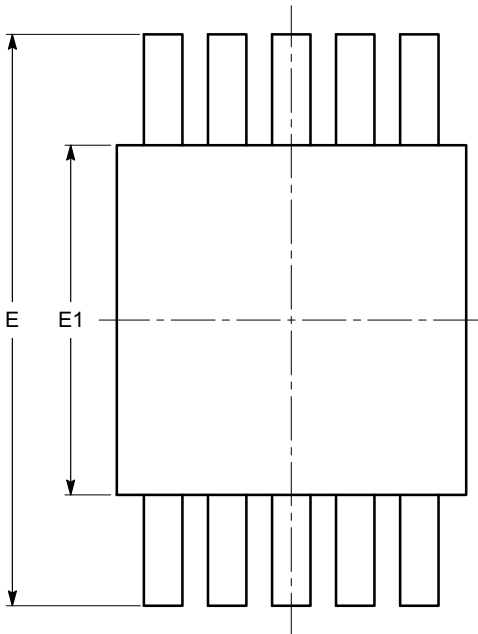
Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-187.

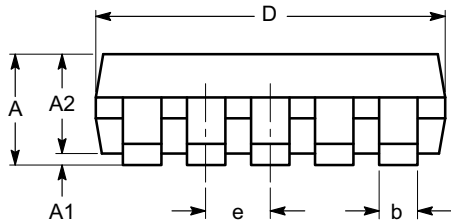
CM1216

PACKAGE DIMENSIONS

MSOP 10, 3x3
CASE 846AE-01
ISSUE O

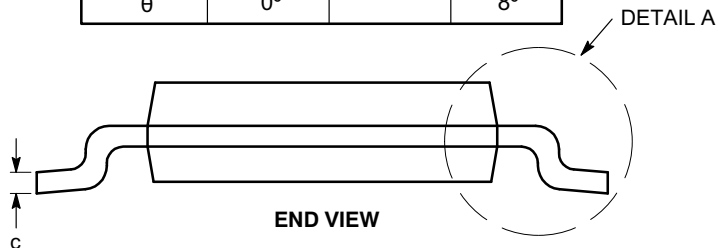


TOP VIEW

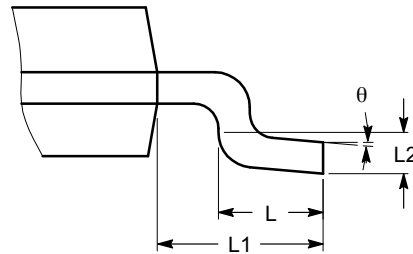


SIDE VIEW

| SYMBOL | MIN | NOM | MAX |
|----------|----------|------|------|
| A | | | 1.10 |
| A1 | 0.00 | 0.05 | 0.15 |
| A2 | 0.75 | 0.85 | 0.95 |
| b | 0.17 | | 0.27 |
| c | 0.13 | | 0.23 |
| D | 2.90 | 3.00 | 3.10 |
| E | 4.75 | 4.90 | 5.05 |
| E1 | 2.90 | 3.00 | 3.10 |
| e | 0.50 BSC | | |
| L | 0.40 | 0.60 | 0.80 |
| L1 | 0.95 REF | | |
| L2 | 0.25 BSC | | |
| θ | 0° | | 8° |



END VIEW




DETAIL A

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MO-187.

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